Panel Session 7:

Power Dissipation During Testing: Should we worry about it?

Coordinator:
S. Chakravarty, SUNY, Buffalo

Moderator:
J. Monzel, IBM

Panelists:
V.D. Agrawal, Bell Labs, Lucent Technologies
R. Aitken, Hewlett-Packard
J. Braden, Stratus Computers
J. Figueras, Universitat Politecnica de Catalunya, Barcelona
S. Kumar, Motorola
H.J. Wunderlich, Universitaet Stuttgart
Y. Zorian, LogicVision

Abstract:

ICs are subjected to higher than normal switching activity during testing. This can potentially cause heating and reliability problems during testing of bare dies for MCMs, battery powered and low voltage devices used in portable systems, automobiles, etc. The panel will discuss the seriousness of this problem and the solutions that have been proposed.